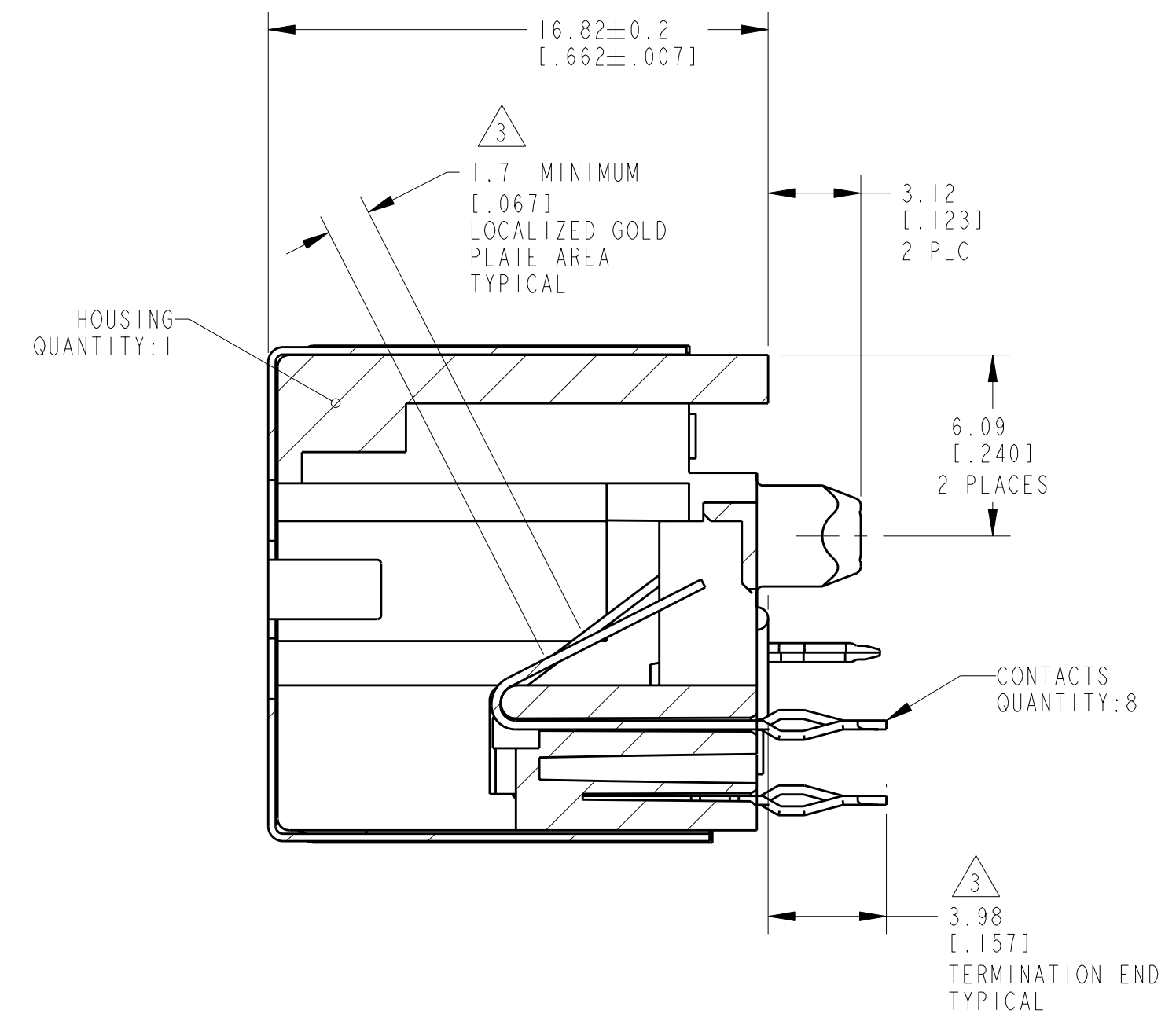
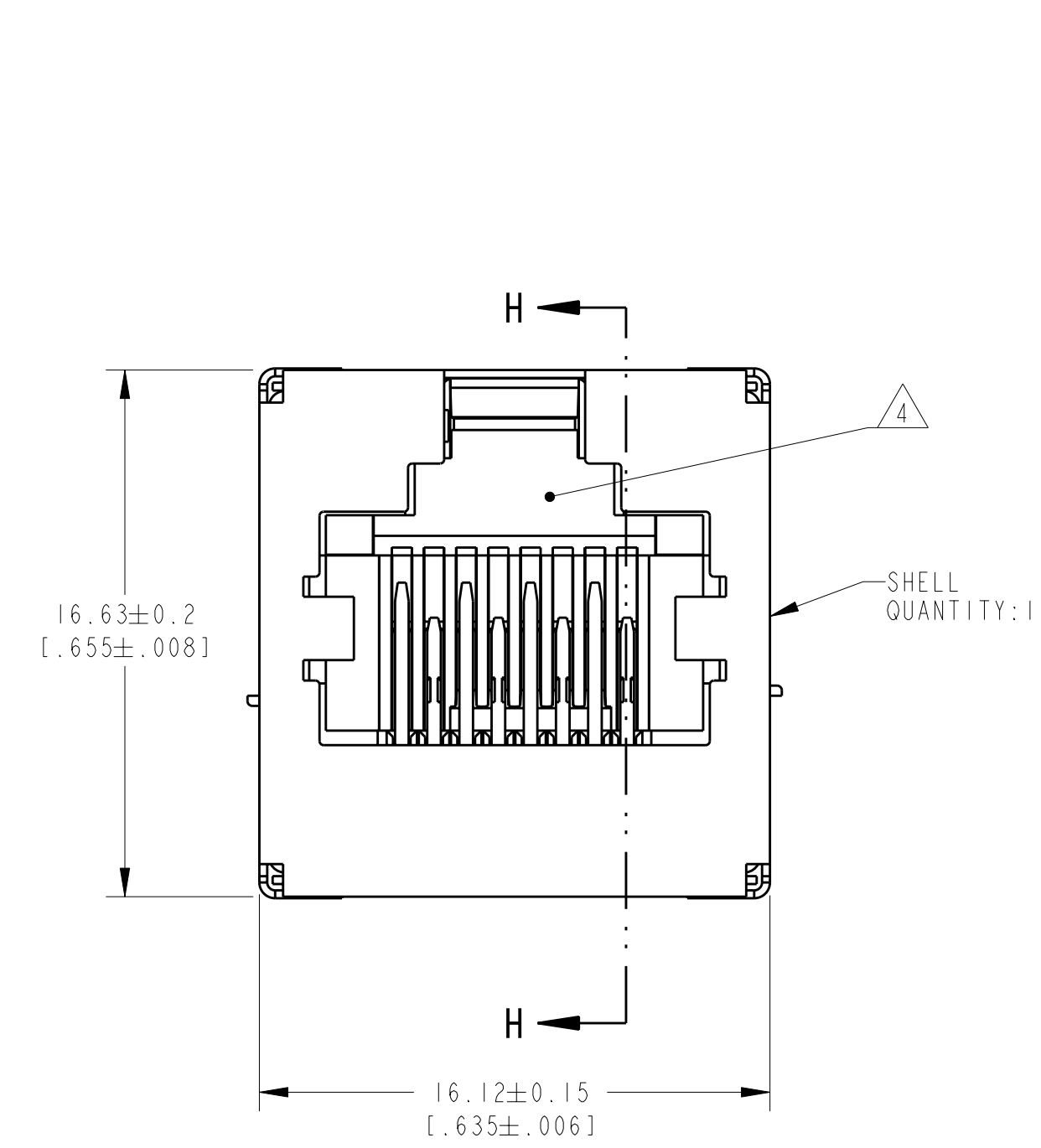
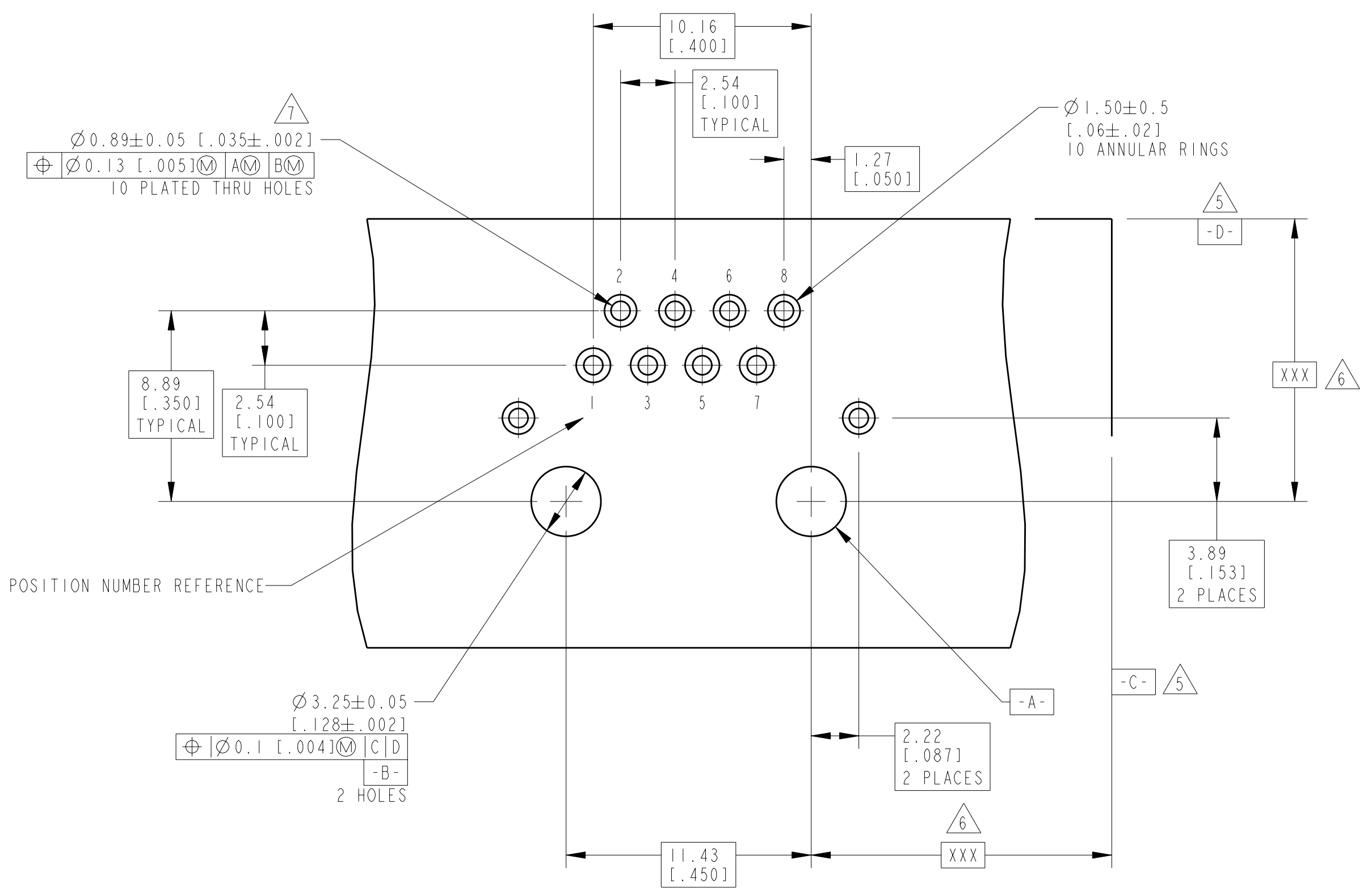


LOC	DIST	REV	DATE	BY	CHK	APPV	DESCRIPTION
AA	22	A	20APR2005	LAM	JW		ECOS11-0201-04
		B	02DEC2005	RG	SF		REV PER ECO-05-014974
		C	20MAR2007	RG	JW		REV PER ECO-07-004617
		D	16AUG2007	LAM	JW		ECO-07-018421

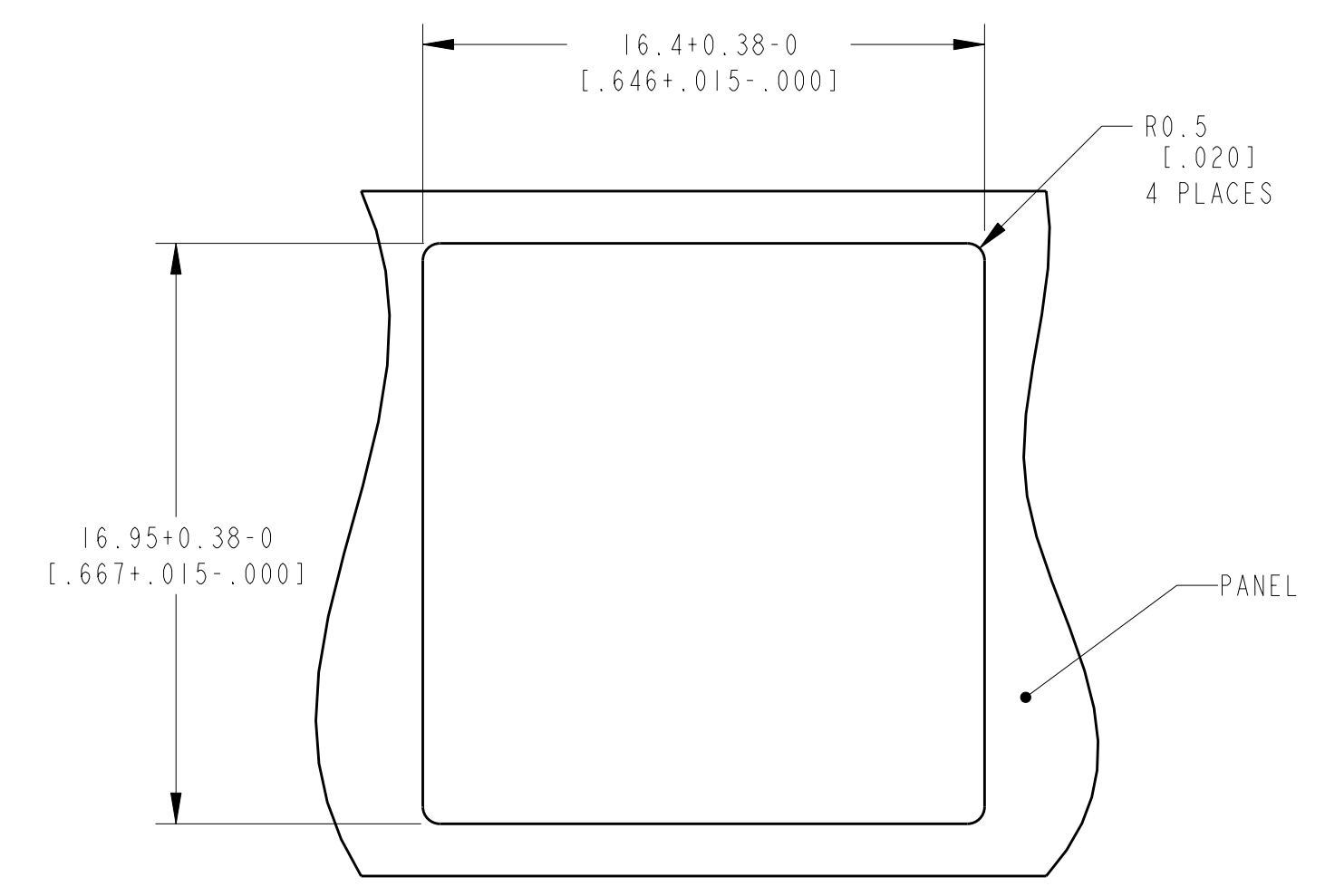
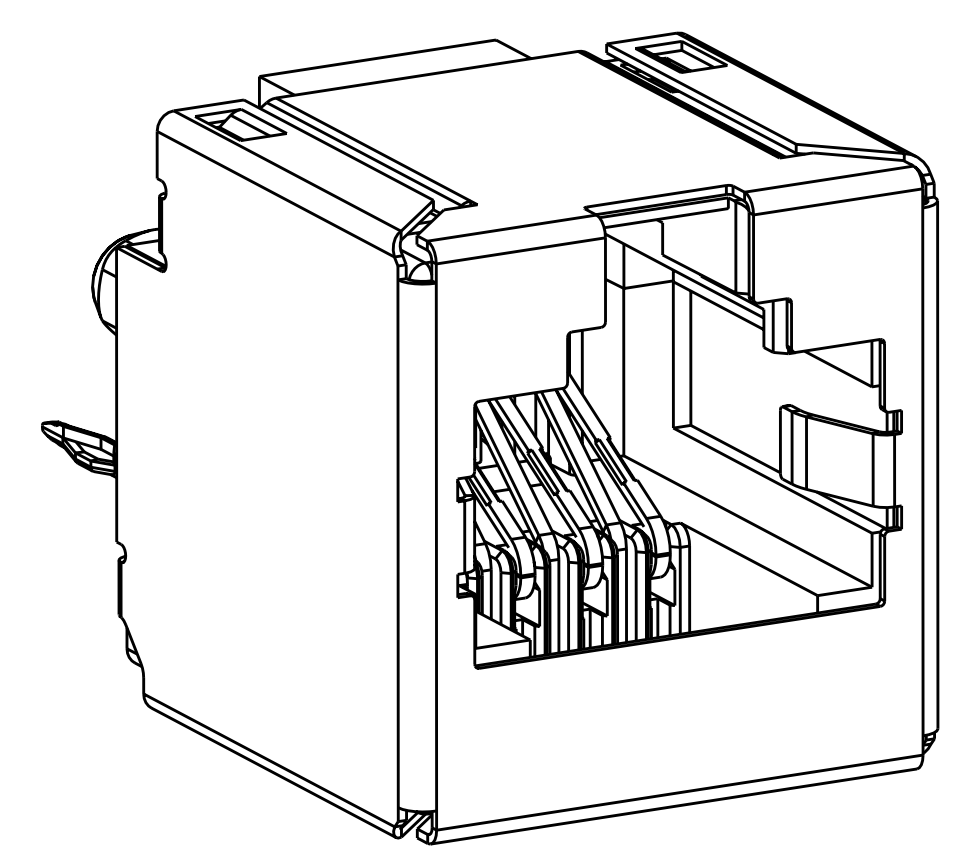


- 1 THERMOPLASTIC.
- 2 PHOSPHOR BRONZE
- 3 1.27 μ m [0.000050] MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2 μ m [0.000079] MIN MATTE TIN ON TERMINATION END, BOTH OVER 1.27 μ m [0.000050] MIN NICKEL.
- 4 CAVITY CONFORMS TO FCC 47 CFR 68 PART F.
- 5 DATUMS ESTABLISHED BY CUSTOMER.
- 6 DIMENSIONS ESTABLISHED BY CUSTOMER.
- 7 DRILLED HOLE DIAMETER 1.02 ± 0.03 [0.040 ± 0.001]. COPPER THK 0.03-0.08 [0.001-0.003]. TIN THICKNESS 8 μ m [0.000315] MIN.
- 8 COPPER ZINC ALLOY
- 9 2.03 μ m [0.000080] MIN BRIGHT TIN OVER 1.27 μ m [0.000050] MIN NICKEL
- 10 PC BOARDS GREATER THAN 1.57 [0.062] IN THICKNESS MAY REQUIRE SPECIAL EXTRACTION TOOLING, CONSULT ENGINEERING.
- 11 PACKAGED 29 PIECES PER TUBE
- 12 PACKAGED 27 PIECES PER TUBE

SECTION H-H



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 RECOMMENDED PRINTED CIRCUIT BOARD THICKNESS 1.4 [0.055] MIN
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD



RECOMMENDED PANEL CUTOUT

PACKAGING	COLOR	PART NUMBER
12	NATURAL	6116202-3
11	NATURAL	6116202-2
11	BLACK	6116202-1

DIMENSIONS: mm [INCHES] TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ±0.3 [0.012] 1 PLC ±0.13 [0.005] 5 PLC ±0.13 [0.005] 4 PLC ±0.13 [0.005] ANGLES ±0.5°		DWN L. A. MAYER 20APR2005 CHK J. WESTMAN 20APR2005 APPV S. FLICKINGER 20APR2005		Tyco Electronics Harrisburg, PA 17105-3608	
MATERIAL: THERMOPLASTIC FINISH: 1.7 MINIMUM LOCALIZED GOLD PLATE AREA TYPICAL		NAME: MODULAR JACK ASSEMBLY, VERTICAL, COMPLIANT PIN, SHIELDED, 8 POSITION, CATEGORY 5		SIZE: 114-2158 WEIGHT: -	
CUSTOMER DRAWING		SCALE: 5:1		SHEET 1 OF 1 REV D	